PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT7151123

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
STMICROELECTRONICS, INC.	01/21/2022

RECEIVING PARTY DATA

Name:	STMICROELECTRONICS INTERNATIONAL N.V.
Street Address:	CHEMIN DU CHAMP-DES-FILLES 39
Internal Address:	PLAN-LES-OUATES
City:	GENEVA
State/Country:	SWITZERLAND
Postal Code:	1228

PROPERTY NUMBERS Total: 10

Property Type	Number
Application Number:	14310601
Application Number:	14310986
Application Number:	14310886
Application Number:	14311150
Application Number:	14975200
Application Number:	14311022
Application Number:	14310633
Application Number:	15253601
Application Number:	62273260
Application Number:	15253618

CORRESPONDENCE DATA

Fax Number: (206)682-6031

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 2066224900
Email: reneeo@seedip.com
Correspondent Name: SEED IP LAW GROUP LLP
Address Line 1: 701 5TH AVE
Address Line 2: SUITE 5400
Address Line 4: SEATTLE, WASHINGTON 98104

ATTORNEY DOCKET NUMBER:	850163.001
NAME OF SUBMITTER:	HAYLEY J. TALBERT
SIGNATURE:	/Hayley J. Talbert/
DATE SIGNED:	01/31/2022

Total Attachments: 10

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ASSIGNMENT

Assignor:	***STMICROELECTRONICS, INC.***
Assignor being a company, corporation, or juristic entity of:	***United States of America***
Assignor's principal place of business:	***750 Canyon Drive, Suite 300, Coppell, Texas, United States of America, 75019***

Assignee:	***STMICROELECTRONICS INTERNATIONAL N.V.***
Assignee being a company, corporation, or juristic entity of:	***Netherlands***
Assignee's principal place of business:	***Chemin du Champ-des-Filles 39, Plan-les-Ouates, Geneva, Switzerland 1228***

WHEREAS, Assignor was assigned certain rights in and to certain inventions, and applications for the Application(s)/Patent(s) listed in the attached Exhibit; and

WHEREAS, Assignee is desirous of acquiring the entire right, title, and interest in and to the inventions and the application for Application(s)/Patent(s) listed in the attached Exhibit, and in and to any patent to be obtained therefor and thereon worldwide.

NOW, THEREFORE, for and in consideration of good and valuable consideration, the receipt, sufficiency, and adequacy of which are hereby acknowledged, Assignor hereby transfers and assigns to Assignee, all of Assignor's rights, title, and interest in and to the following:

(a) the Application(s)/Patent(s) listed in the attached Exhibit together with the inventions for which the Application(s)/Patent(s) listed in the attached Exhibit is/was (are/were) made and describes (collectively "the Patent Rights");

(b) all provisional applications, patent applications, patents, or other similar governmental grants or issuances, in any jurisdiction in the world, (i) from which the Patent Rights directly or indirectly claims priority and/or (ii) for which the Patent Rights directly or indirectly forms a basis for priority;

(c) any continuations, continuations-in-part, continuing prosecution applications, requests for continuing examinations, divisionals, reissues, reexaminations, extensions, and registrations, in any jurisdiction in the world, of any provisional patent application, patent application, patent, or other governmental grant or issuance set forth in clauses (a) and/or (b) (clauses (a) through (c), collectively the "Assigned Patent Rights");

(d) any causes of action (whether currently pending, filed, or otherwise) and all other enforcement rights and rights to remedies under, on account of, or related to, any of the Assigned Patent Rights, including, without limitation, all causes of action and other enforcement rights for (i) damages, (ii) injunctive relief, and (iii) other remedies of any kind for past, current, and future infringement or misappropriation in violation of rights, and all rights to sue for any of the foregoing; and

(e) any and all other rights and interests in any jurisdiction in the world arising out of the Assigned Patent Rights, including, but not limited to, any right to claim priority thereto and/or therefrom.

All of the rights, title, and interest assigned above shall be held and enjoyed by the Assignee for its own use and enjoyment and for the use and enjoyment of its successors and assigns to the full end of the applicable term for which the aforementioned rights may be granted in any jurisdiction in the world.

Assignor hereby further agrees to assist in, sign, and execute all documents needed or desired, now or in the future, to perfect, obtain, and secure the aforementioned rights to Assignee and its successors for any jurisdiction in the world. At the expense of Assignee or its successors, Assignor agree to assist in any legal proceedings, sign all lawful papers, make all lawful oaths, and generally do everything possible to aid Assignee and its affiliates or their successors, as well as their legal representatives, to enforce the aforementioned rights in any jurisdiction in the world.

Assignor hereby grant Assignee, along with the following Assignee representatives, the power to insert in this Assignment any further identification that may be necessary or desirable in order to comply with the rules for recordation of this document in any jurisdiction in the world: All practitioners at USPTO Customer Number 38106.

If part or all of Assignor's rights, title, and interest arising out of the Assigned Patent Rights are already owned by Assignee, or its successor(s)/predecessor(s), because (i) Assignor is or was already subject to an obligation to assign such rights, title, and interest to Assignee, or its successor(s)/predecessor(s), by an agreement, company policy, applicable law, or otherwise, and/or (ii) such rights, title, and interest have already been assigned by operation of law to Assignee, or its successor(s)/predecessor(s), in accordance with applicable law, and/or (iii) such rights, title, and interest were, from their inception, automatically owned by Assignee, or its successor(s)/predecessor(s), under applicable law, then this document further memorializes, documents, and confirms such prior ownership by Assignee, or its successor(s)/predecessor(s), of such rights, title, and interest for all purposes, including for recording purposes in any jurisdiction in the world.

Assignor and Assignee confirm and agree that a notarized and/or legalized translation copy of this document in any other language shall have the same force and effect in any jurisdiction in the world as if such translation copy were an original thereof.

The signatures of all the signers need not appear on the same page, and each signer may sign this Assignment in multiple counterparts, such that collectively all the necessary signatures of each separately signed counterpart of this Assignment constitutes an original Assignment. A paper or electronic copy of a signature page shall have the same force and effect as if such copy were an original thereof.

Assignor
STMICROELECTRONICS, INC.

Signature: ______________________

Print Name: Kevin Fruip

Title: V.P. and General Counsel

Date: January 21, 2022

Acknowledged and accepted by:
Assignee
STMICROELECTRONICS INTERNATIONAL N.V.

Signature: ______________________

Print Name: ______________________

Title: ______________________

Date: ______________________

EXHIBIT

Country	Application No.	Patent No.	Title
US	14/310,601	10,264,667	MICROFLUIDIC DELIVERY SYSTEM WITH A DIE ON A RIGID SUBSTRATE
US	16/287,949		MICROFLUIDIC DELIVERY SYSTEM WITH A DIE ON A RIGID SUBSTRATE
CN	201510301051.2	ZL201510301051.2	MICROFLUIDIC DELIVERY SYSTEM WITH A DIE ON A RIGID SUBSTRATE
CN	201520379068.5	ZL201520379068.5	MICROFLUIDIC DELIVERY SYSTEM WITH A DIE ON A RIGID SUBSTRATE
US	14/310,986	9,259,754	MICROFLUIDIC DELIVERY MEMBER WITH FILTER AND METHOD OF FORMING SAME
US	14/981,056	9,357,635	MICROFLUIDIC DELIVERY MEMBER WITH FILTER AND METHOD OF FORMING SAME
US	15/138,997	9,561,657	MICROFLUIDIC DELIVERY MEMBER WITH FILTER AND METHOD OF FORMING SAME
US	14/310,633	9,174,445	MICROFLUIDIC DIE WITH A HIGH RATIO OF HEATER AREA TO NOZZLE EXIT AREA
US	14/310,886	9,358,567	MICROFLUIDIC SYSTEM WITH SINGLE DRIVE SIGNAL FOR MULTIPLE NOZZLES
CN	201510303530.8	ZL201510303530.8	MICROFLUIDIC SYSTEM WITH SINGLE DRIVE SIGNAL FOR MULTIPLE NOZZLES
CN	201520382453.5	ZL201520382453.5	MICROFLUIDIC SYSTEM WITH SINGLE DRIVE SIGNAL FOR MULTIPLE NOZZLES
US	14/975,540	9,919,334	MICROFLUIDIC SYSTEM WITH SINGLE DRIVE SIGNAL FOR MULTIPLE NOZZLES
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US	15/636,491	10,543,504	MICROFLUIDIC SYSTEM WITH SINGLE DRIVE SIGNAL FOR MULTIPLE NOZZLES
US	15/803,630	10,646,892	MICROFLUIDIC SYSTEM WITH SINGLE DRIVE SIGNAL FOR MULTIPLE NOZZLES
US	14/311,150	9,861,720	MICROFLUIDIC DELIVERY SYSTEM AND METHOD
US	14/975,200	9,968,700	MICROFLUIDIC DELIVERY SYSTEM AND METHOD
US	14/311,022	9,174,453	MICROFLUIDIC REFILL CARTRIDGE HAVING A VENT HOLE AND A NOZZLE PLATE ON SAME SIDE
US	62/273,260	N/A	SEMI-FLEXIBLE SUPPORT
US	15/253,601	10,272,684	SUPPORT SUBSTRATES FOR MICROFLUIDIC DIE
US	16/357,077	10,759,168	SUPPORT SUBSTRATES FOR MICROFLUIDIC DIE
US	16/357,100	10,759,169	SUPPORT SUBSTRATES FOR MICROFLUIDIC DIE
US	16/945,465		SUPPORT SUBSTRATES FOR MICROFLUIDIC DIE

Country	Application No.	Patent No.	Title
US	15/253,618	10,118,391	MICROFLUIDIC DIE ON A SUPPORT WITH AT LEAST ONE OTHER DIE
US	16/179,808	10,836,167	MICROFLUIDIC DIE ON A SUPPORT WITH AT LEAST ONE OTHER DIE

ASSIGNMENT

Assignor:	***STMICROELECTRONICS, INC.***
Assignor being a company, corporation, or juristic entity of:	***United States of America***
Assignor's principal place of business:	***750 Canyon Drive, Suite 300, Coppell, Texas, United States of America, 75019***

Assignee:	***STMICROELECTRONICS INTERNATIONAL N.V.***
Assignee being a company, corporation, or juristic entity of:	***Netherlands***
Assignee's principal place of business:	***Chemin du Champ-des-Filles 39, Plan-les-Ouates, Geneva, Switzerland 1228***

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(e) any and all other rights and interests in any jurisdiction in the world arising out of the Assigned Patent Rights, including, but not limited to, any right to claim priority thereto and/or therefrom.

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Assignor
STMICROELECTRONICS, INC.

Signature: ______________________

Print Name: ______________________

Title: ______________________

Date: ______________________

Acknowledged and accepted by:
Assignee
STMICROELECTRONICS INTERNATIONAL N.V.

Signature: ______________________

Print Name: Patrick C. R. Holmes

Title: Attorney-in-Fact

Date: January 27, 2022

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